

2SJ531 Silicon P Channel MOS FET

REJ03G0881-0300 (Previous: ADE-208-646A) Rev.3.00 Sep 07, 2005

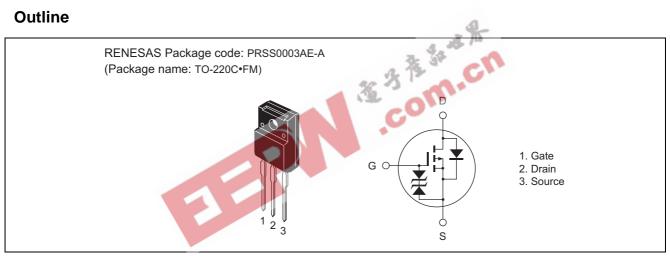
Description

High speed power switching

Features

- Low on-resistance $R_{DS(on)} = 0.050 \Omega$ typ.
- Low drive current.
- 4 V gate drive devices.
- High speed switching.

Outline





Absolute Maximum Ratings

			(Ta = 25°C)
Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	-60	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	ID	-18	A
Drain peak current	I _{D (pulse)} Note 1	-72	A
Body to drain diode reverse drain current	I _{DR}	-18	A
Avalanche current	I _{AP} Note 3	-18	A
Avalanche energy	E _{AR} Note 3	27	mJ
Channel dissipation	Pch Note 2	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	۵°C

Notes: 1. PW \leq 10 µs, duty cycle \leq 1%

2. Value at Tc = 25°C

3. Value at Tch = 25° C, Rg $\geq 50 \Omega$

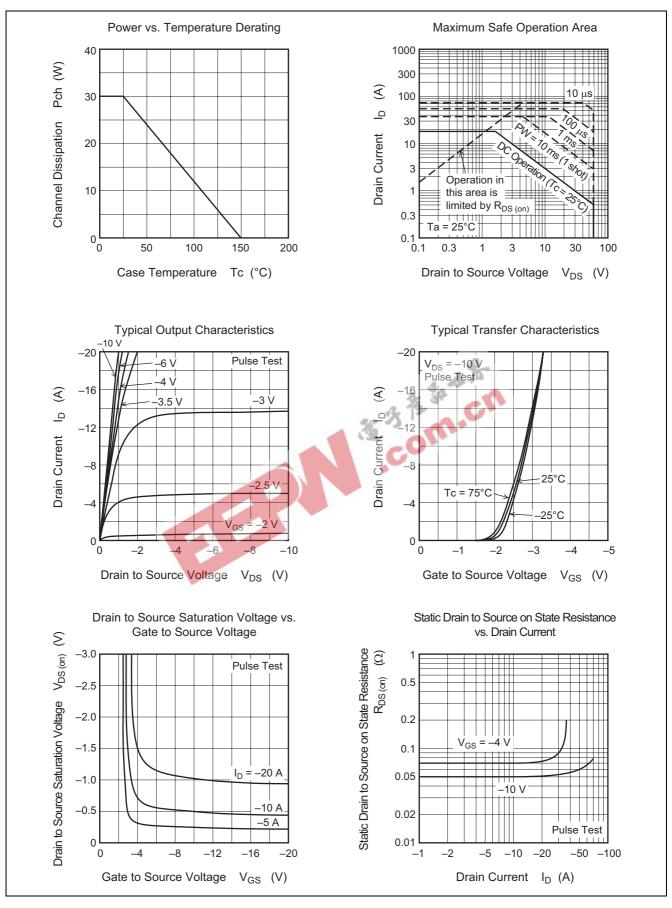
Electrical Characteristics

						(Ta = 25°C)
ltem	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V (BR) DSS	-60		_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V (BR) GSS	±20	_	4	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	a	-10	μΑ	$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0$
Gate to source leak current	I _{GSS}		<u>x</u> 3	±10	μA	$V_{GS} = \pm 16 V, V_{DS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-1.0		-2.0	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	R _{DS (on)}	+	0.050	0.065	Ω	$I_D = -9 \text{ A}, V_{GS} = -10 \text{ V}^{Note 4}$
	R _{DS (on)}	1	0.070	0.110	Ω	$I_D = -9 A, V_{GS} = -4 V^{Note 4}$
Forward transfer admittance	y _{fs}	10	16	—	S	$I_D = -9 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note 4}}$
Input capacitance	Ciss	_	1300	—	pF	$V_{DS} = -10 V$
Output capacitance	Coss	—	650	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	180	—	pF	f = 1 MHz
Turn-on delay time	t _{d (on)}	_	14	—	ns	$V_{GS} = -10 \text{ V}$
Rise time	tr	_	95	—	ns	$I_D = -9 A$
Turn-off delay time	t _{d (off)}	_	190	—	ns	$R_L = 3.33 \ \Omega$
Fall time	t _f	_	135	—	ns	
Body to drain diode forward voltage	V_{DF}	_	-1.0	—	V	$I_F = -18 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	70	_	ns	$I_F = -18 \text{ A}, V_{GS} = 0$
						di _F /dt = 50 A/µs

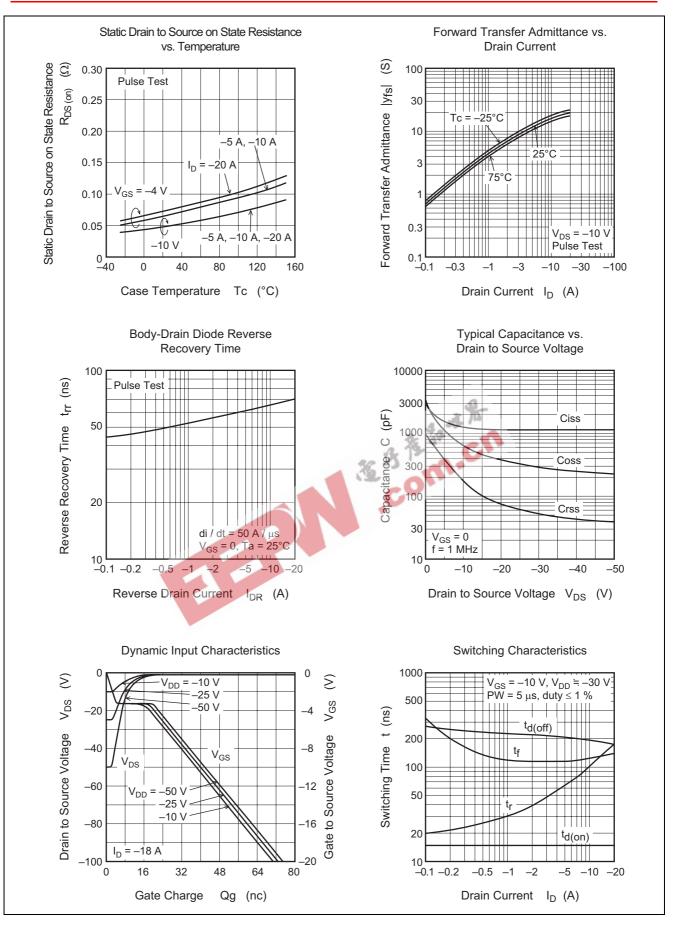
Note: 4. Pulse test



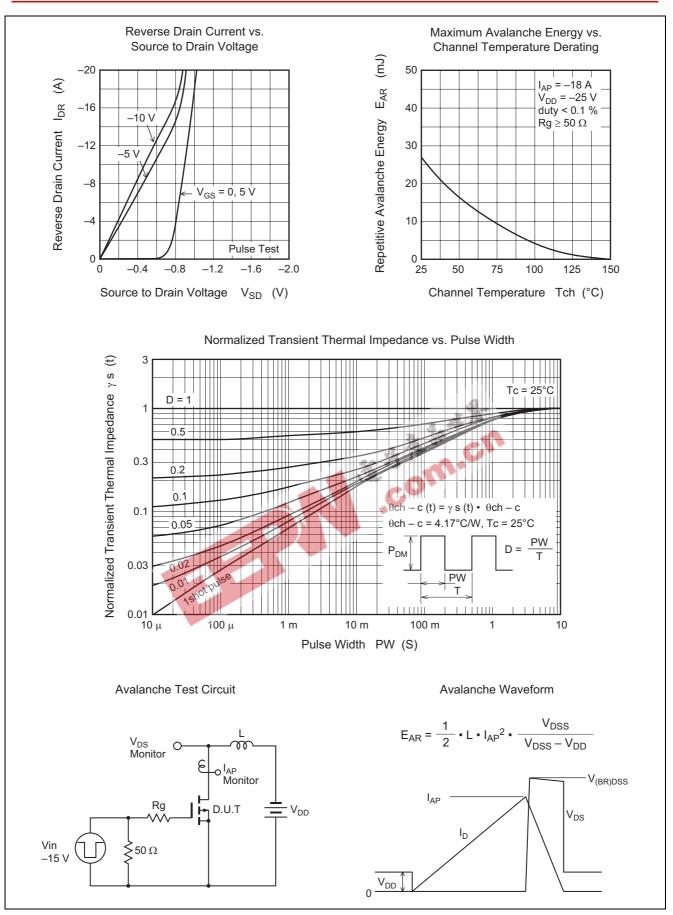
Main Characteristics



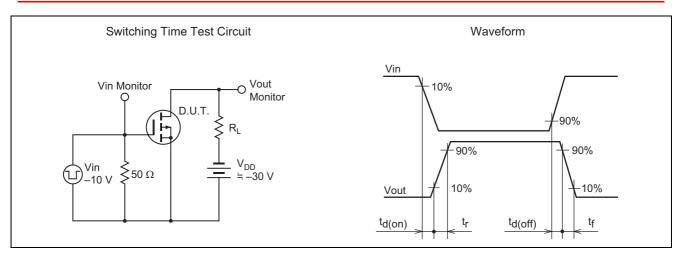








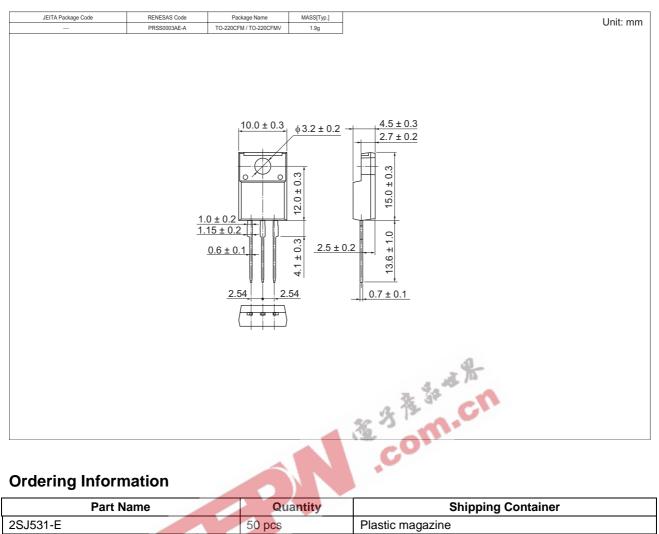








Package Dimensions



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